

06-03-1999

Q9/155208

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Attached original documents or copy thereof.

To the Honorable Commissioner of I

1. Name of conveying party(ies):

Kenichi Morizono  
Keiji Okada  
Hiromi Shigemoto  
Hideshi Kawachi

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: Mitsui Chemicals, Inc.

Internal Address:

300 Rec'd PCT/PTO 24 SEP 1998

Street Address: 2-5, Kasumigaseki, 1-chome

Chiyoda-ku, Tokyo 100, Japan

City: State: ZIP:

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other

Execution Date: August 18, 1998

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: August 18, 1998

A. Patent Application No.(s)

09/155208

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Leonard W. Sherman

Internal Address: Sherman and Shalloway

Street Address: 413 N. Washington Street

City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

19-1980

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Leonard W. Sherman  
Name of Person Signing

September 24, 1998  
Date

Total number of pages including cover sheet, attachments, and document:

2

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments PATENT  
Washington, D.C. 20231

REEL: 9824 FRAME: 0854

A S S I G N M E N T

WHEREAS, I/WE, (1) Kenichi MORIZONO, Keiji OKADA, Hiromi SHIGEMOTO and Hideshi KAWACHI, residing at (2) c/o MITSUI CHEMICALS, INC., 1-2, Waki 6-chome, Waki-cho, Kuga-gun, Yamaguchi 740, Japan for 1st & 2nd persons, and c/o MITSUI CHEMICALS, INC., 3, Chigusa-Kaigan, Ichihara-shi, Chiba 299-01, Japan (hereinafter referred to as INVENTOR(S)), am/are the sole or joint inventor (if more than one inventor is named below) of subject matter (Invention) disclosed in (for 3rd & 4th persons) an application for United States Letters Patent titled (3) ADHESIVE RESIN COMPOSITIONS AND LAMINATES USING THE COMPOSITIONS FOR ADHESIVE LAYERS which was executed by me/us on (4) \_\_\_\_\_, and filed in the United States Patent and Trademark Office on (5) \_\_\_\_\_, under Serial No. (6) N/A, in the name(s) of (7) \_\_\_\_\_, and which has issued on (8) N/A as U.S. Patent No. (9) N/A; and

WHEREAS, MITSUI CHEMICALS, INC. having its principal place of business at 2-5, Kasumigaseki 3-chome, Chiyoda-ku, \*\*\* (hereinafter referred to as company), is desirous of acquiring my/our entire undivided interest in and to said Invention and in and to any Letters Patent that may be granted therefor in the United States and in any and all foreign countries.

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventor(s) has/have sold, assigned and transferred, and by the presents do/does sell, assign and transfer unto said company my/our entire undivided interest in the said Invention in the United States and its territorial possessions and in all foreign countries and my/our entire undivided right, title and interest in and to any and all Letters Patent, which may be granted hereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

I hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said company as the assignee of my/our entire undivided rights, title and interest in and to the same, for the sole use and behoof of the said company, its successors and assigns.

FURTHER, I/WE agree that I/we will communicate to said company or its representatives any facts known to me/us respecting said Invention and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said company, make all rightful oaths and generally do everything possible to aid said company, its successors and assigns, to obtain and enforce proper protection for said Invention to the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, I/WE have hereunto set my/our hand this 18th day of August, 1998

Signed in the presence of:

Witness: Naoko Okazaki Signed: Kenichi Morizono  
Witness: Akemi Fujiwara Signed: Keiji Okada  
Witness: \_\_\_\_\_ Signed: Hiromi Shigemoto  
Signed: Hideshi Kawachi

\*\*\* Tokyo 100, Japan